

In the Abstract

Please replace the Abstract with the following amended abstract:

A method is provided for bonding a microelectronic element is with a connection component having a polymeric body, the method including and a bonding material is provided between contacts on the microelectronic element and conductive features of the connection component. The microelectronic element is heated so as to activate the bonding material, and then cooled, leaving said contacts on said microelectronic element bonded to the said conductive features on the connection component. The connection component is maintained at an average temperature below the glass transition temperature of the polymer in the connection component during the heating and cooling steps.